



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20251126000.1

**Qualification of TI Philippines as Additional Assembly/Test site for select devices
Change Notification / Sample Request**

Date: November 26, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251126000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA365AIDBVR	OPA365AIDBVR
OPA365AIDBVT	OPA365AIDBVT

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251126000.1	PCN Date:	November 26, 2025
Title:	Qualification of TI Philippines as Additional Assembly/Test site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	February 24, 2026	Sample requests accepted until:	January 25, 2026*
*Sample requests received after January 25, 2026 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
PCN Details			
Description of Change:			
Texas Instruments is pleased to announce the qualification of TI Philippines (PHI) as an additional Assembly and Test site for the list of devices shown below. Material differences between sites are as follows.			
	Current site	Additional site	
	TFME	PHI	
Assembly Site	1.0mil Au	0.8mil Cu	
Bond wire diam/type	SID#R-13	4222198	
Mold Compound	SID#A-03	4226215	
Mount Compound	NiPdAuAg	Post-Plate Ag Spot	
Lead Finish	Cu	CuAg, HyDe	
Lead Frame			
Qual details are provided in the Qual Data Section. Test coverage, insertions, conditions will remain consistent with current testing.			
Reason for Change:			
Supply Continuity			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
Assembly Site Information:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Chongchuan
PHI	PHI	PHL	Baguio City

Sample product shipping label (not actual product label)

 TEXAS
INSTRUMENTS

MADE IN: Malaysia
2DC: 2Q:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:

ITEM:

LBL: 5A (L)T0:1750

 G4



(1P) SN74LS07NSR

(Q) 2000 (D) 0336

(31T) LOT: 3959047MLA

(4W) TKY (1T) 7523483SI2

(P)

(2P) REV: (V) 0033317

(20L) CSO: SHE (21L) CCO: USA

(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

OPA365AIDBVR	OPA365AIDBVT		
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For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Report

Approve Date 19-November-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA365AID BVR	QBS Package Reference TPS26610D DFR	QBS Process Reference ALM2403QP W/PRQ1	QBS Package Reference OPA328D BVT	QBS Package Reference TLV1805QD BVRQ1	QBS Reference: AMC1305M25QD W/RQ1	QBS Package Reference TPS79301DB V/RM/Q1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	-	3/231/0	-
UHAST	A3	Autodave	121C/15psig	96 Hours	-	3/231/0	-	-	-	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	1/77/0	3/231/0	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	3/231/0	-	3/231/0	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	3/135/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	1/45/0	-	-	1/45/0	-
HTSL	A6	High Temperature Storage Life	Per QSS-009-018 420 Hours, 170C	1 Step	-	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	-	-	1/77/0
HTOL	B1	Life Test	140C	1000 Hours	-	-	3/230/0	-	-	-	-
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: OPA365AID BVR	QBS Package Reference TPS26610D DFR	QBS Process Reference ALM2403QP W/PRQ1	QBS Package Reference OPA328D BVT	QBS Package Reference TLV1805QD BVRQ1	QBS Reference: AMC1305M25QD W/RQ1	QBS Package Reference TPS79301DB V/RM/Q1
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	-	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	3/66/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	3/66/0	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/30/0	3/15/0	3/30/0	3/30/0	3/30/0
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-	-	-	1/3/0
ESD	E2	ESD CDM	-	750 Volts	-	-	-	-	-	1/3/0	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	-	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	4000 Volts	1/3/0 ¹	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD 78	-	1/6/0 ¹	-	1/6/0	1/6/0	-	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0	3/90/0	3/90/0	3/90/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device OPA365AID BVR is qualified at MSL 1 260C

- Preconditioning was performed for Autodave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2407-033
 [1] QBS to the OPA365AQBVRQ1

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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